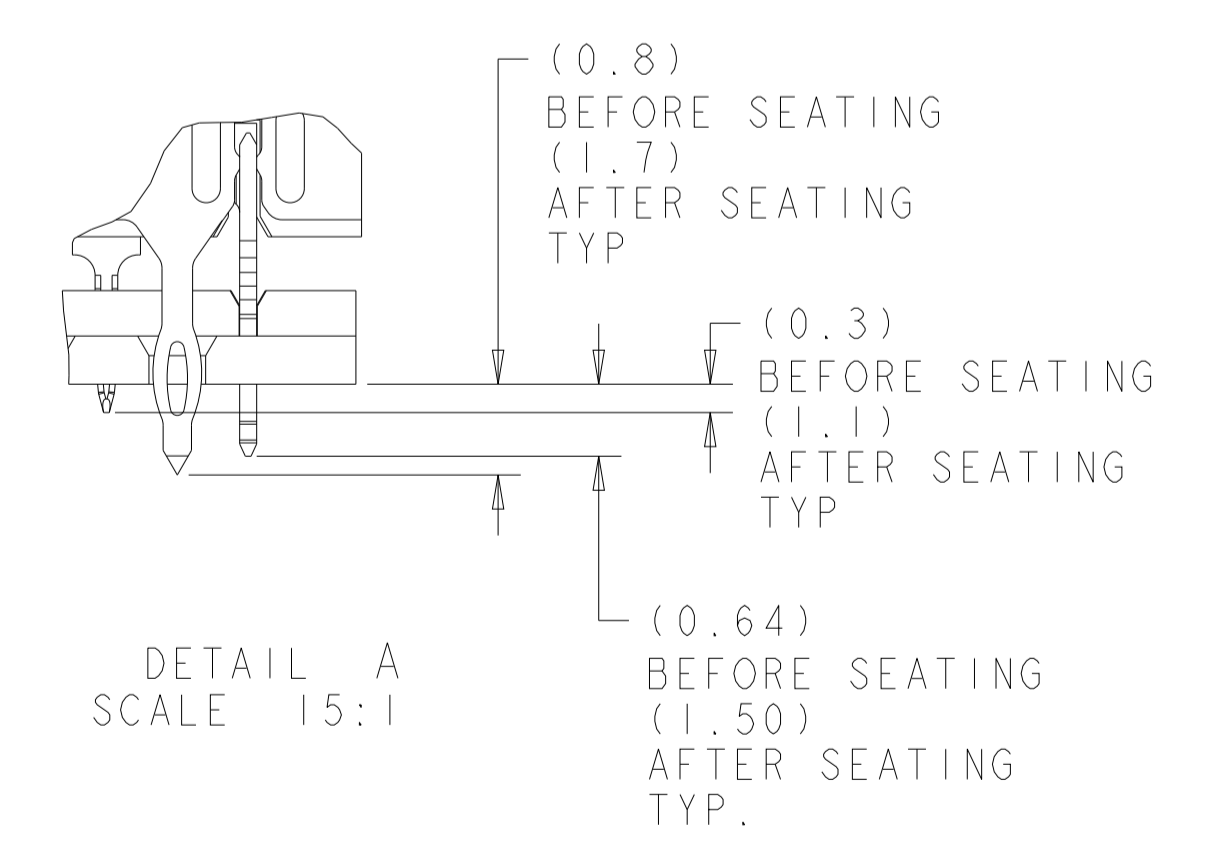
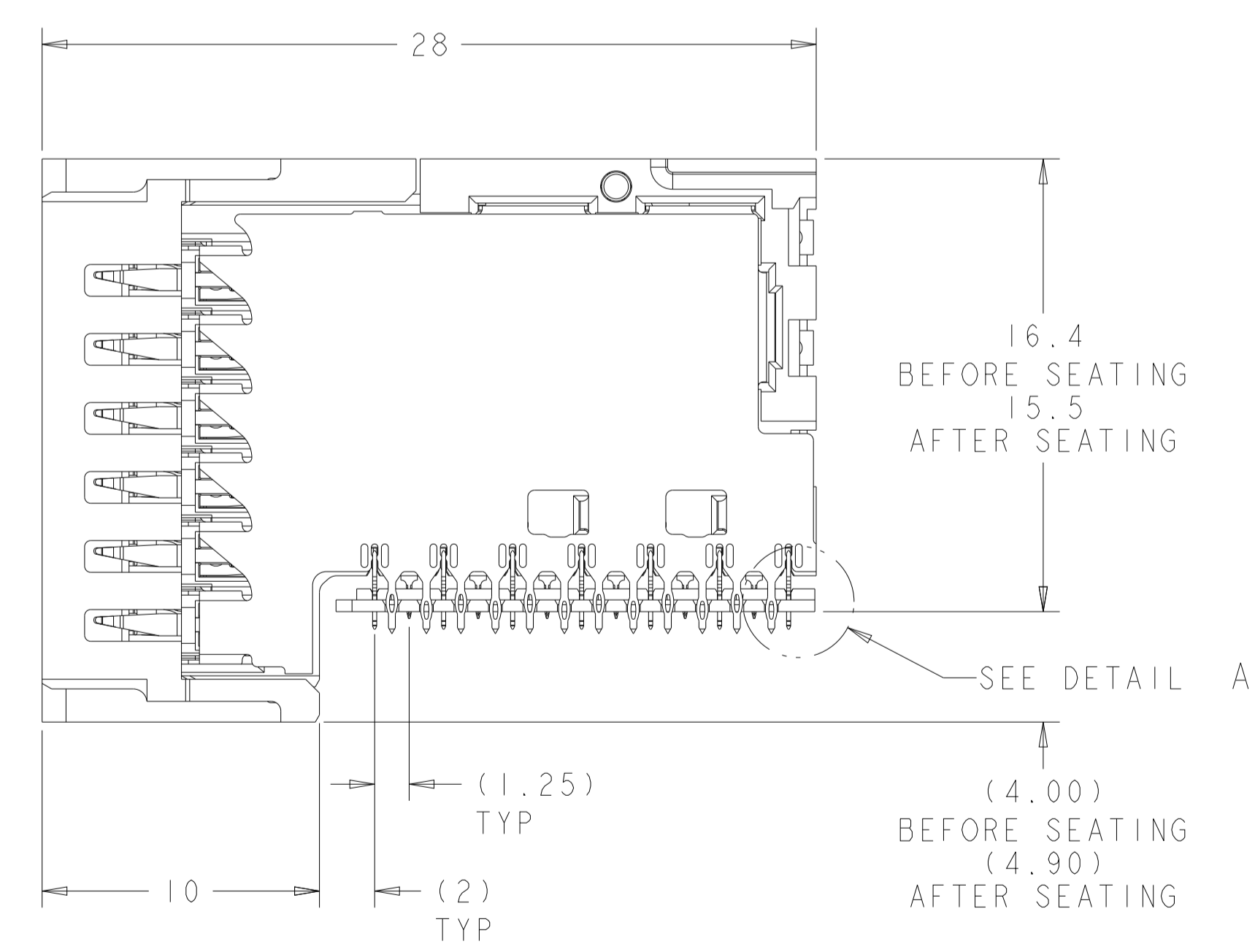
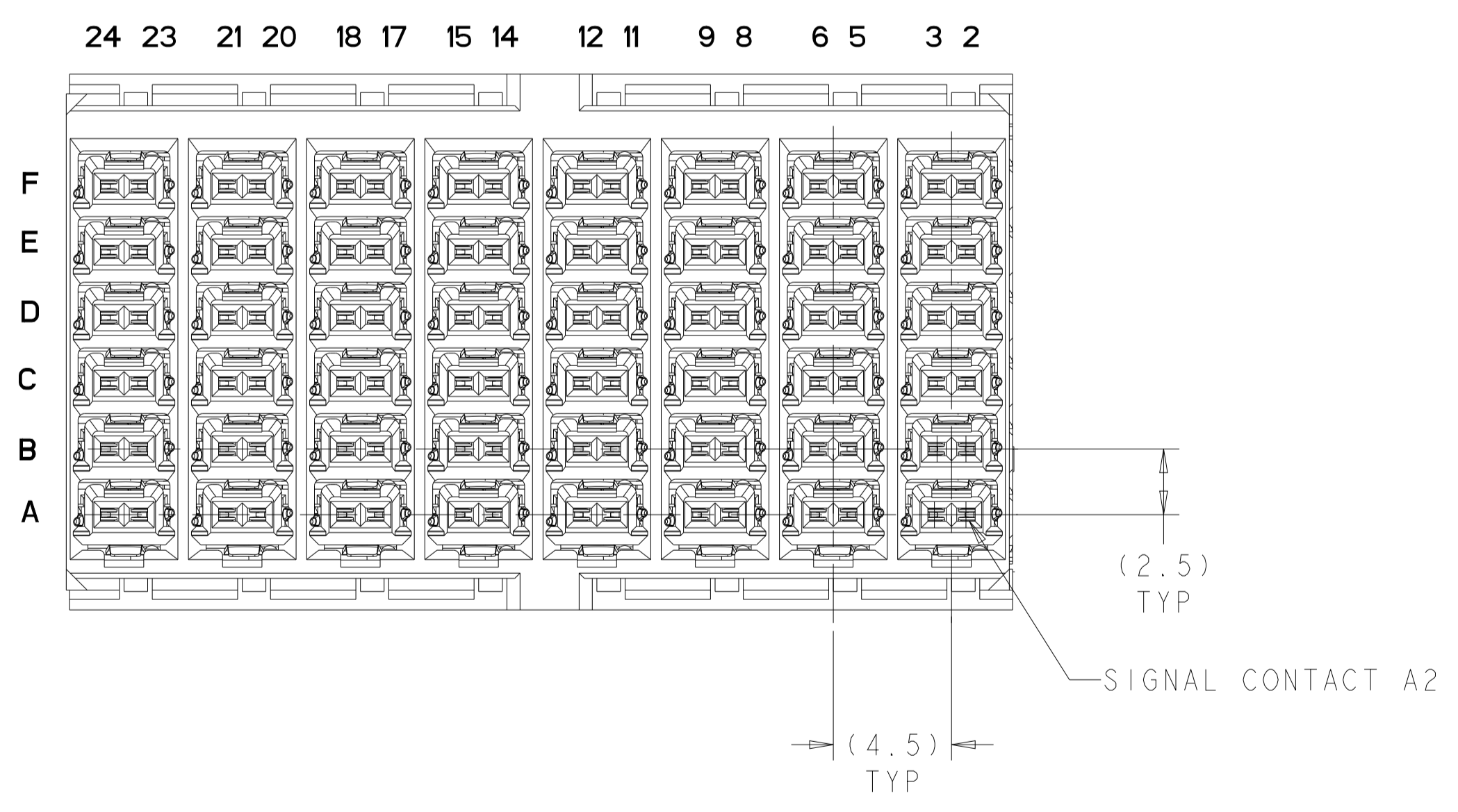
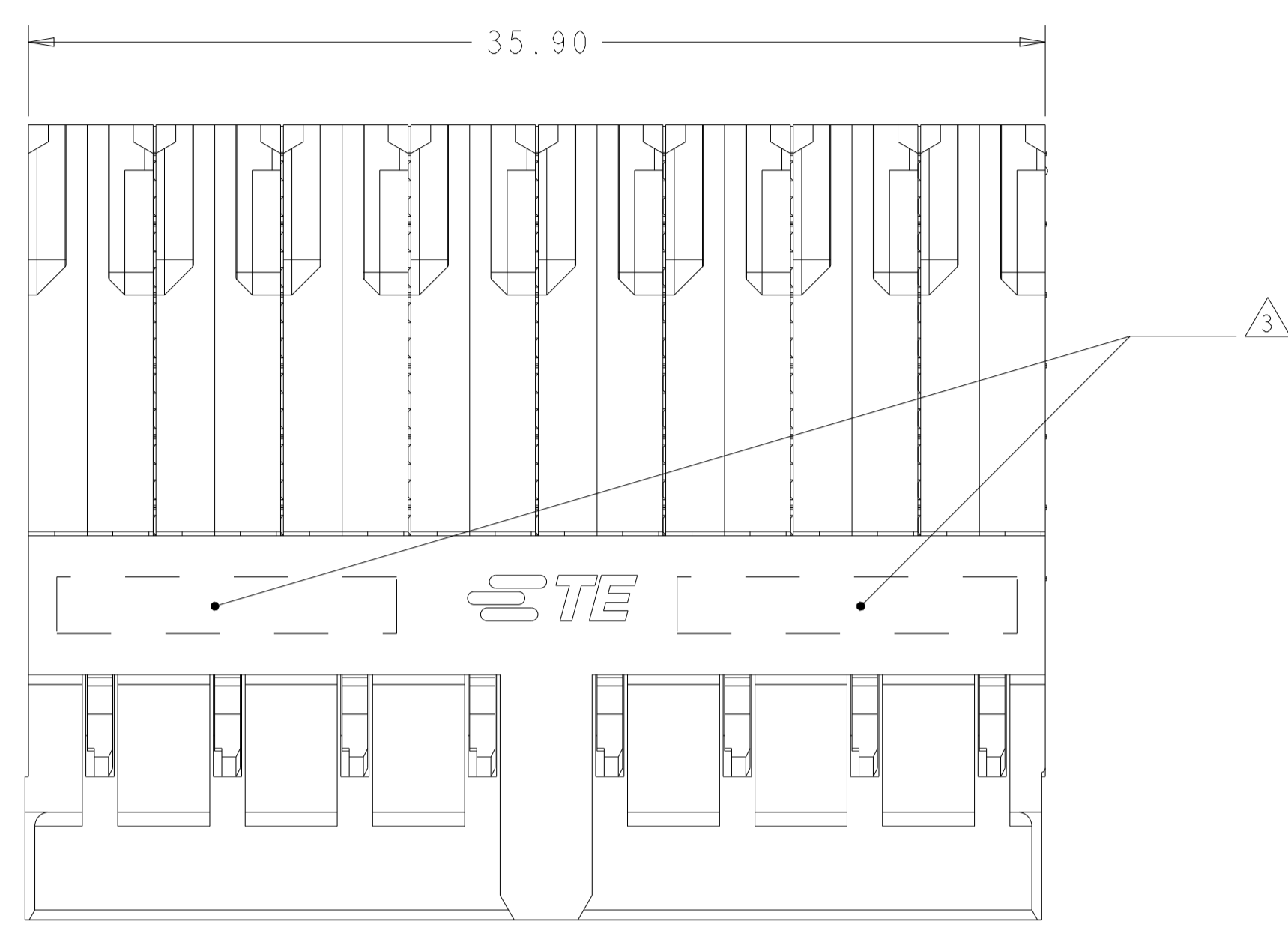


LOC	DIST	REVISIONS					
GP	00	P	LTN	DESCRIPTION	DATE	DWN	APVD
		A		PRELIMINARY	23MAR2014	RT	NS
		B		REVISED PER ECO-17-006848	10MAY2017	JM	SS
		C		REVISED PER ECN-24-258247	29MAR2024	RZ	HL

- △ MATERIAL:
CONTACT AND SHIELD - COPPER ALLOY.
HOUSINGS, AND ORGANIZER - THERMOPLASTIC, UL 94V-0, BLACK.
- △ CONFORMS TO REQUIREMENTS OF TE PRODUCT SPECIFICATION 108-2413, BASED ON TELCORDIA GR-1217-CORE FOR SYSTEM QUALITY LEVEL III; APPLICATIONS IN CONTROLLED ENVIRONMENTS (CENTRAL OFFICE).
- △ CONNECTOR MARKED WITH PART NUMBER, DATE CODE, AND OPTIONAL MANUFACTURING LOCATION IDENTIFICATION CODE IN APPROXIMATE AREA SHOWN.
- 4. CONTACT AREA LUBRICATED WITH BELLCORE APPROVED LUBRICANT. TECHNICAL REFERENCE: GR-1217-CORE, ISSUE 2, DECEMBER 2008.
- △ PLATED THRU HOLE REQUIREMENTS:
FINISHED HOLE = $\varnothing 0.344 \pm 0.039$
DRILLED HOLE = $\varnothing 0.420 \pm 0.013$
COPPER THICKNESS = 0.038 ± 0.013
IMMERSION TIN IF APPLICABLE = 0.00051 ± 0.00013
- △ PLATED THRU HOLE REQUIREMENTS:
FINISHED HOLE = $\varnothing 0.244 \pm 0.039$
DRILLED HOLE = $\varnothing 0.320 \pm 0.013$
COPPER THICKNESS = 0.038 ± 0.013
IMMERSION TIN IF APPLICABLE = 0.00051 ± 0.00013
- △ PTH DIMENSIONS APPLY TO 1.00mm DEPTH FROM MOUNT SIDE OF PCB.
- △ HOLE POSITION TOLERANCE APPLIES WITHIN PATTERN FOR CONNECTOR PATTERN TO CONNECTOR PATTERN, A 0.12 \varnothing POSITION TOLERANCE APPLIES.

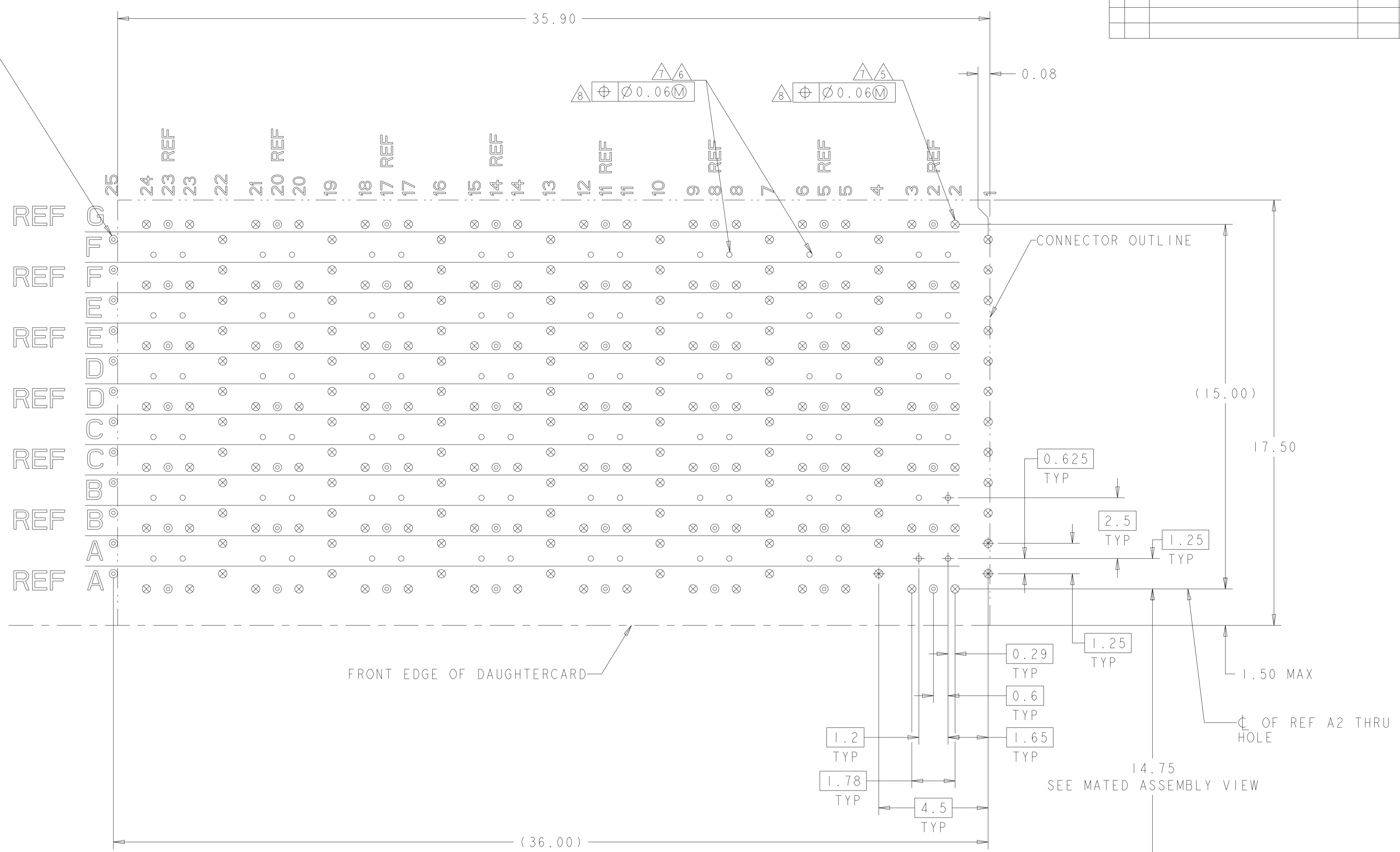


OBSELETE	TIN	2198266-2
	TIN-LEAD	2198266-1
	PRESS FIT	PART NO
	TAIL PLATING	

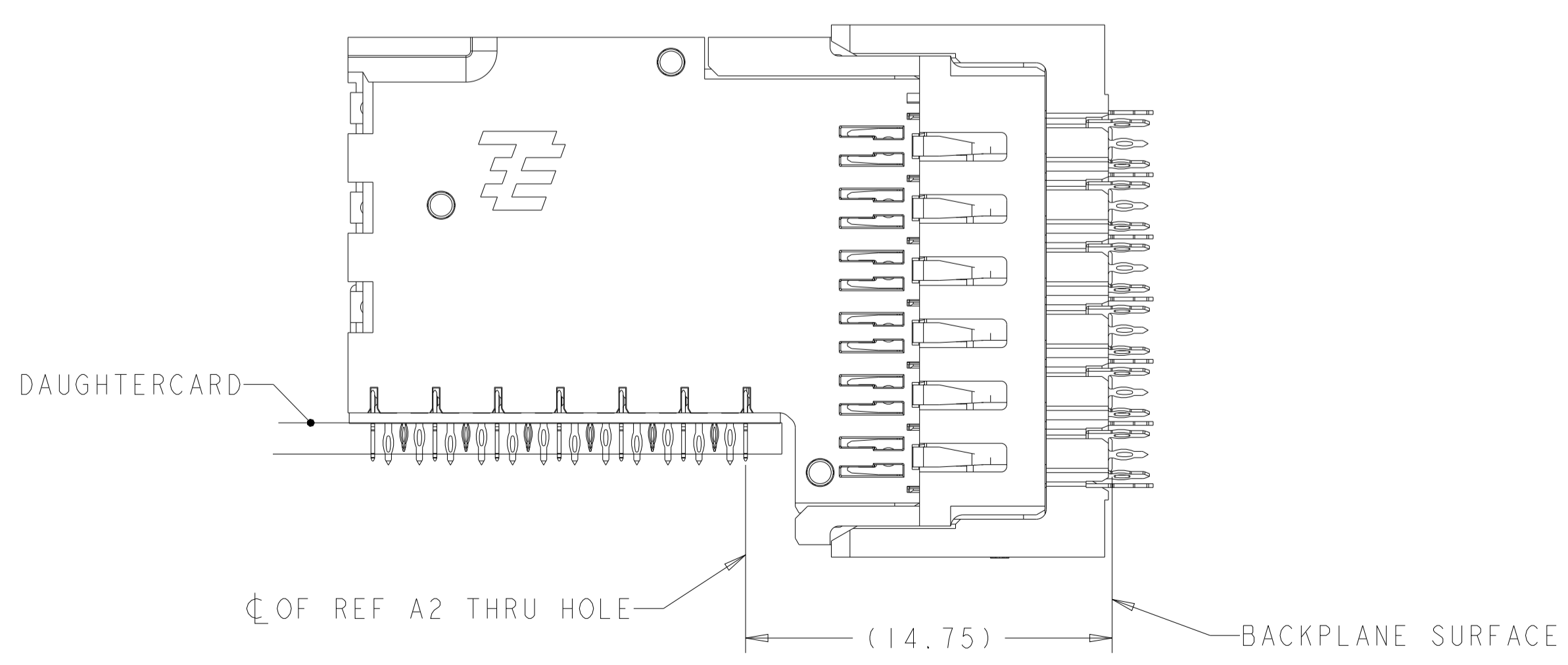
THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN: R. THOMPSON 29NOV2011	TE Connectivity
DIMENSIONS: mm		CHK: N. SWANGER 29NOV2011	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD: N. SWANGER 29NOV2011	NAME: RECEPTACLE ASSEMBLY, 6 PAIR 8 COLUMN, RIGHT ANGLE, 4.5mm PITCH, STRADA WHISPER 360
0 PLC ±0.2		PRODUCT SPEC: △	
1 PLC ±0.2		APPLICATION SPEC:	
2 PLC ±0.08		SIZE: 114-13301	
3 PLC ±0.08		WEIGHT: -	RESTRICTED TO:
4 PLC ±0.13		Customer Drawing	A100779C=2198266
ANGLES: °		SCALE: 5:1	SHEET 1 OF 2
FINISH: SEE TABLE		REV: C	

LOC	DIST	REVISIONS					
GP	00	P	LYR	DESCRIPTION	DATE	OWN	APVD
		-		SEE SHEET 1			

FOOTPRINT SHOWN IS FOR SINGLE MODULE APPLICATION. WHEN CONNECTORS ARE STACKED SIDE BY SIDE, THESE SI VIAS ARE USED AS GROUNDS BY THE NEXT CONNECTOR



- = SIGNAL
- ⊗ = GROUND
- ⊙ = SIGNAL INTEGRITY VIA TO GROUND



MATED ASSEMBLY VIEW
SCALE 5:1

PCB LAYOUT
COMPONENT SIDE SHOWN
SCALE 10:1

BACKPLANE MATE SURFACE

THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN K. THOMPSON 29NOV2011	TE Connectivity RECEPTACLE ASSEMBLY, 6 PAIR 8 COLUMN, RIGHT ANGLE, 4.5mm PITCH, STRADA WHISPER 360
DIMENSIONS:		CHK N. SWANGER 29NOV2011	
mm	0 PLC ±0.2 1 PLC ±0.2 2 PLC ±0.08 3 PLC ±0.013 4 PLC ± ANGLES ±°	APVD N. SWANGER 29NOV2011	NAME
TOLERANCES UNLESS OTHERWISE SPECIFIED:		PRODUCT SPEC	APPLICATION SPEC
MATERIAL		WEIGHT	RESTRICTED TO
FINISH		Customer Drawing	SCALE 5:1 SHEET 2 OF 2 REV C